



Materials Declaration

Package	PGA
Body Size	
Lead Count	100
Option	Pb-free

Combolid

Item	% of Combolid	Weight (g)	PPM
Kovar	92.0	4.05E-01	41101
Nickel	4.0	1.76E-02	1787
Gold	4.0	1.76E-02	1787
Subtotal		4.40E-01	44675

Lid Frame

Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	1.43 E-02	1454
Sn	20.42	3.68 E-03	373
Subtotal		1.80 E-02	1828

Ceramic Package

Item	% of Ceramic	Weight (g)	PPM
Ceramics			
Al2O3	90.50	7.24 E+00	735115
Cr2O3	3.90	3.12 E-01	31679
SiO2	3.50	2.80 E-01	28430
TiO2	1.00	8.00 E-02	8123
CaO	0.60	4.80 E-02	4874
MgO	0.50	4.00 E-02	4061
Metallization			
Tungsten	99.37	5.12 E-01	51961
Molybdenum	0.63	3.24 E-03	329
Pin			
Iron	54.0	3.65 E-01	37010
Nickel	29.0	1.96 E-01	19876
Cobalt	17.0	1.15 E-01	11651
Coating 1			
Ag	85.0	6.38 E-02	6473
Cu	15.0	1.13 E-02	1142
Coating 2			
Nickel	92.0	3.13 E-02	3176
Cobalt	8.0	2.72 E-03	276
Subtotal		9.30 E+00	944176

Bond Wires

Item	% of Wire	Weight (g)	PPM
Aluminum	100.0	2.00 E-02	2031

Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	2.58 E-02	2620

Die Attach Paste

Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80.0	7.20 E-03	731
Cyanate ester resin	20.0	1.80 E-03	183
Subtotal		9.00 E-03	914

External Pin Coating/Plating

Item	% of Plating	Weight (g)	PPM
Gold	100.0	3.70 E-02	3757

Package Totals

Weight (g)	PPM
9.85 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

